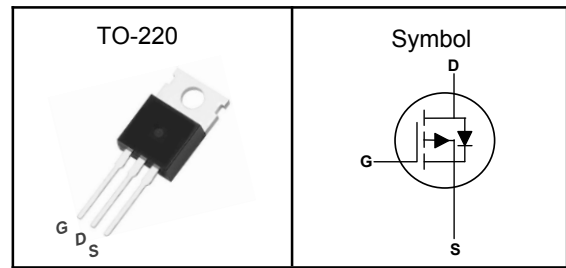


**P-Channel Enhancement Mode MOSFET**
**Features**

- Low  $R_{ds(on)}$  for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

**Applications**

- Power Management in Desktop Computer
- DC/DC Converters

**Pin Description**


$V_{DSS}$	-60	V
$R_{DS(ON)-Typ}$	12	m $\Omega$
$I_D$	-58	A

**Absolute Maximum Ratings** ( $T_C=25^{\circ}C$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	-60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^{\circ}C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}C$
$I_{DM}^{①}$	Pulse Drain Current Tested	-250	A
$I_D$	Continuous Drain Current	-58	A
$P_D$	Maximum Power Dissipation	114	W
$E_{AS}$	Single Pulse Avalanche Energy	450	mJ

**Thermal Characteristics**

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	62	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	1.1	$^{\circ}C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^{\circ}C$ .

Note ③ : Surface Mounted on  $1in^2$  FR-4 board with 1oz.

**P-Channel Enhancement Mode MOSFET****Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$ , Unless Otherwise Noted)

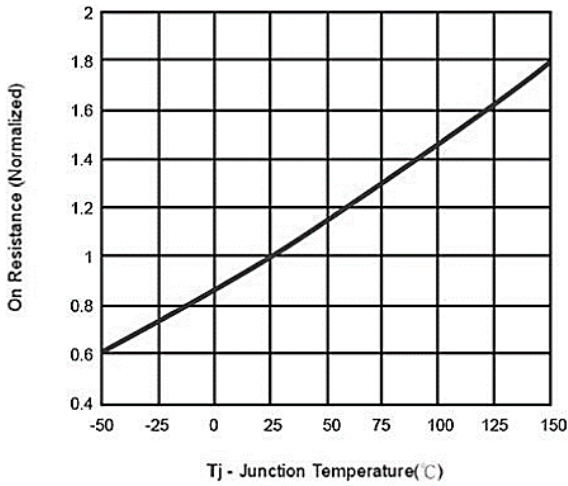
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-60	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-60V, V_{GS}=0V$	---	---	-1	$\mu A$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	---	-2.5	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=-10V, I_D=-20A$	---	12	16	m $\Omega$
		$V_{GS}=-4.5V, I_D=-10A$	---	15	18	
$g_{fs}$	Forward Transconductance	$V_{DS}=-10V, I_D=-80A$	---	---	---	S
<b>Dynamic Characteristics</b> <sup>⑤</sup>						
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=-15V,$ Freq.=1MHz	---	4710	---	pF
$C_{oss}$	Output Capacitance		---	373	---	
$C_{rss}$	Reverse Transfer Capacitance		---	336	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=-30V,$ $V_{GS}=-10V, R_G=6\Omega,$	---	53	---	nS
$T_r$	Turn-on Rise Time		---	19	---	
$T_{d(off)}$	Turn-off Delay Time		---	221	---	
$T_f$	Turn-off Fall Time		---	61	---	
$Q_g$	Total Gate Charge	$V_{DS}=-30V,$ $V_{GS}=-10V, I_D=-50A$	---	94	---	nC
$Q_{gs}$	Gate-Source Charge		---	18	---	
$Q_{gd}$	Gate-Drain Charge		---	24	---	
<b>Source-Drain Characteristics</b>						
$V_{SD}$ <sup>④</sup>	Diode Forward Voltage	$I_S=-17A, V_{GS}=0V$	---	---	-1.2	V

Note ④: Pulse test (pulse width 300 $\mu s$ , duty cycle 2%).

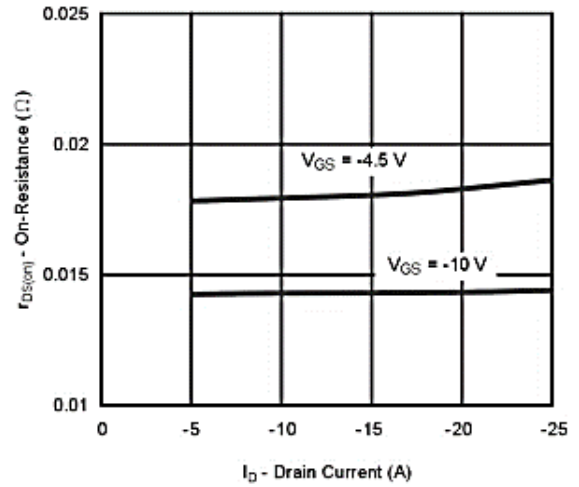
Note ⑤: Guaranteed by design, not subject to production testing.

**P-Channel Enhancement Mode MOSFET**

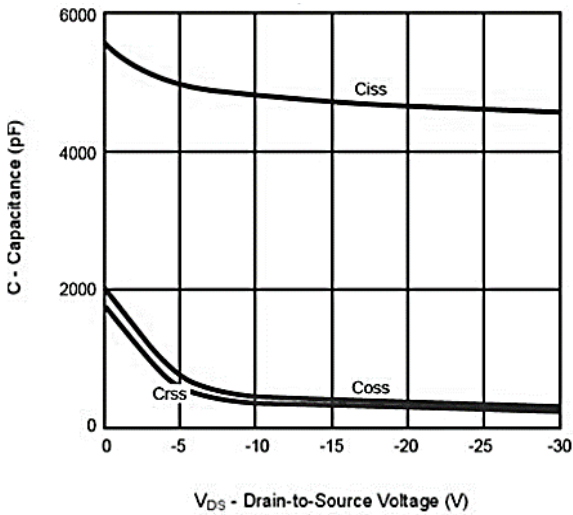
**Typical Characteristics**



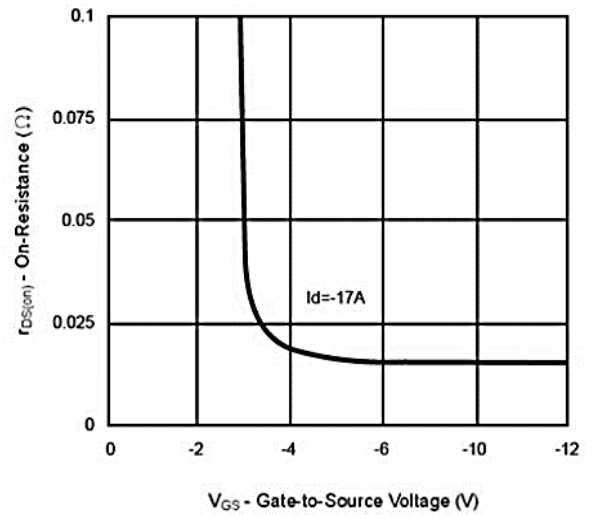
**Fig.1 On Resistance Vs Junction Temperature**



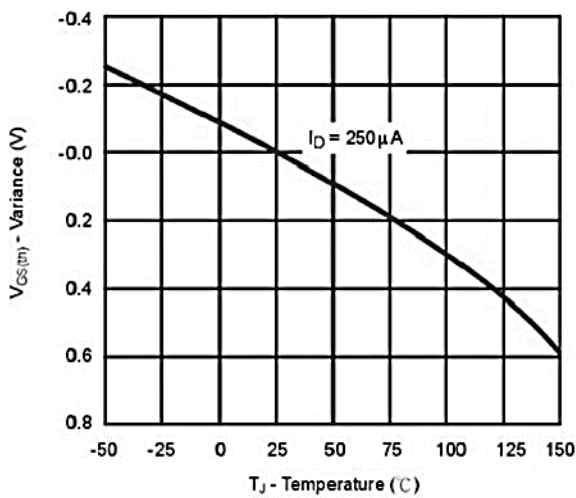
**Fig.2 On-Resistance Vs. Drain Current**



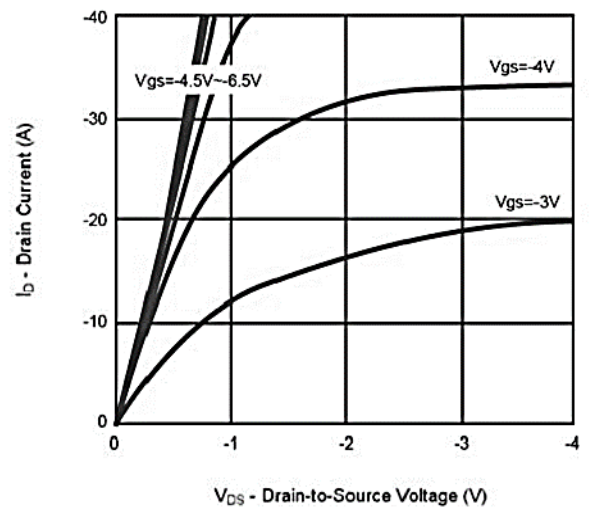
**Fig.3 Capacitance**



**Fig.4 On-Resistance Vs. Gate-to-Source Voltage**

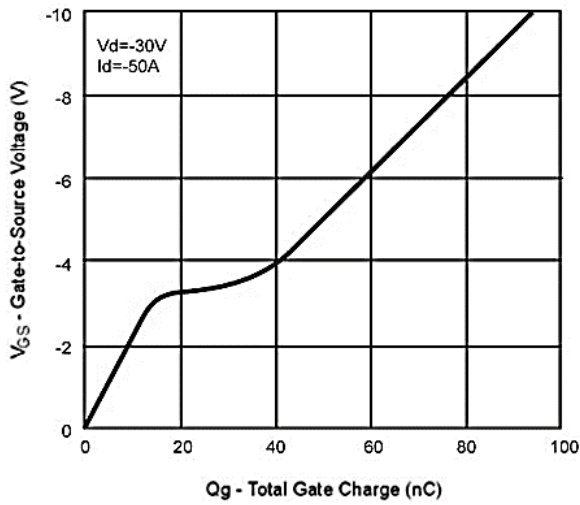


**Fig.5 Threshold Voltage**

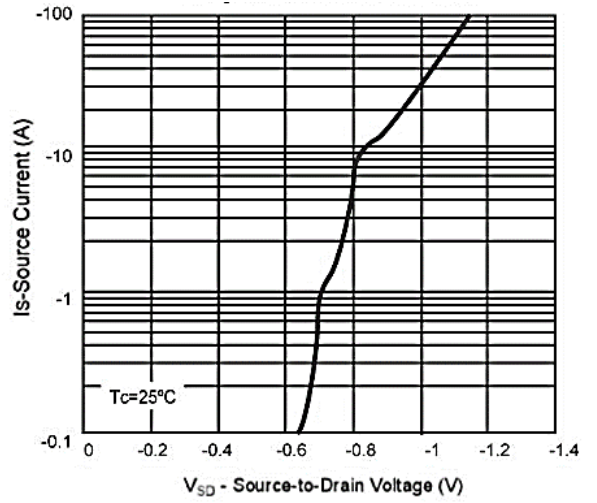


**Fig.6 On-Region Characteristics**

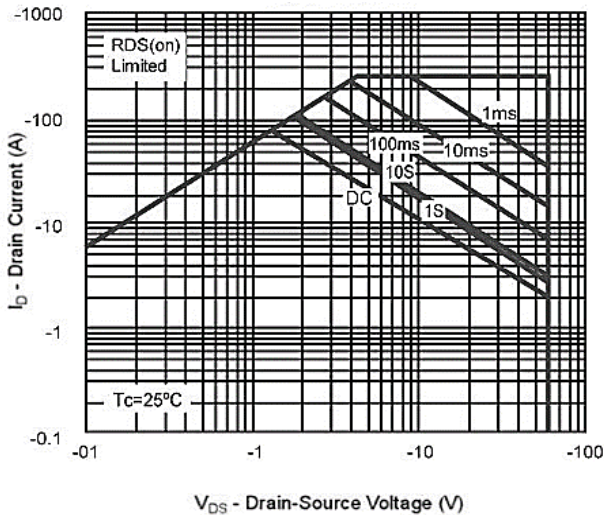
**P-Channel Enhancement Mode MOSFET**



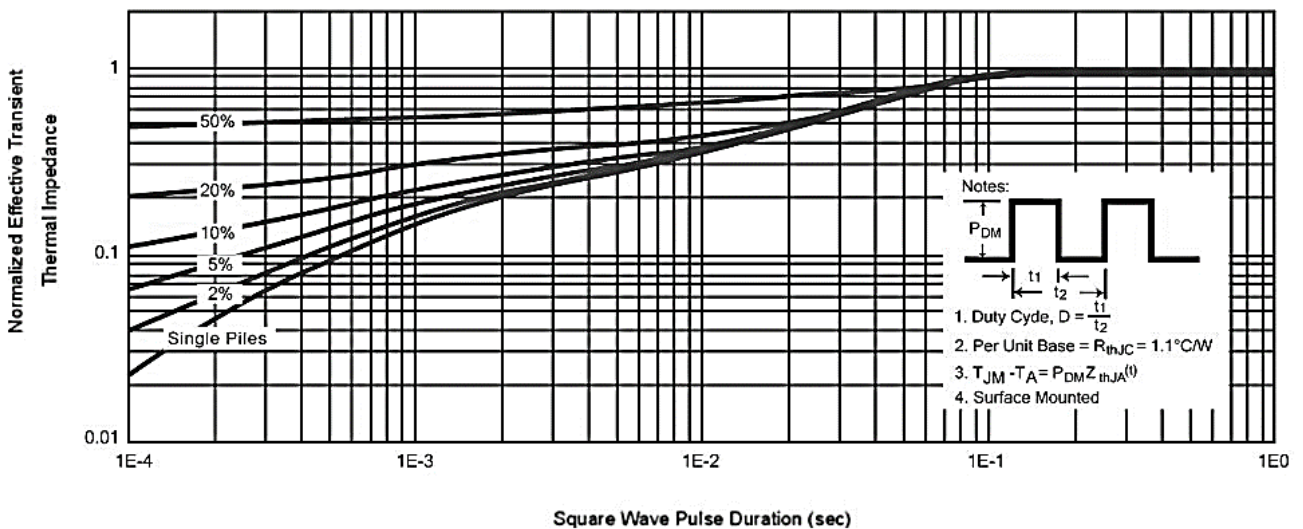
**Fig.7 Gate Charge**



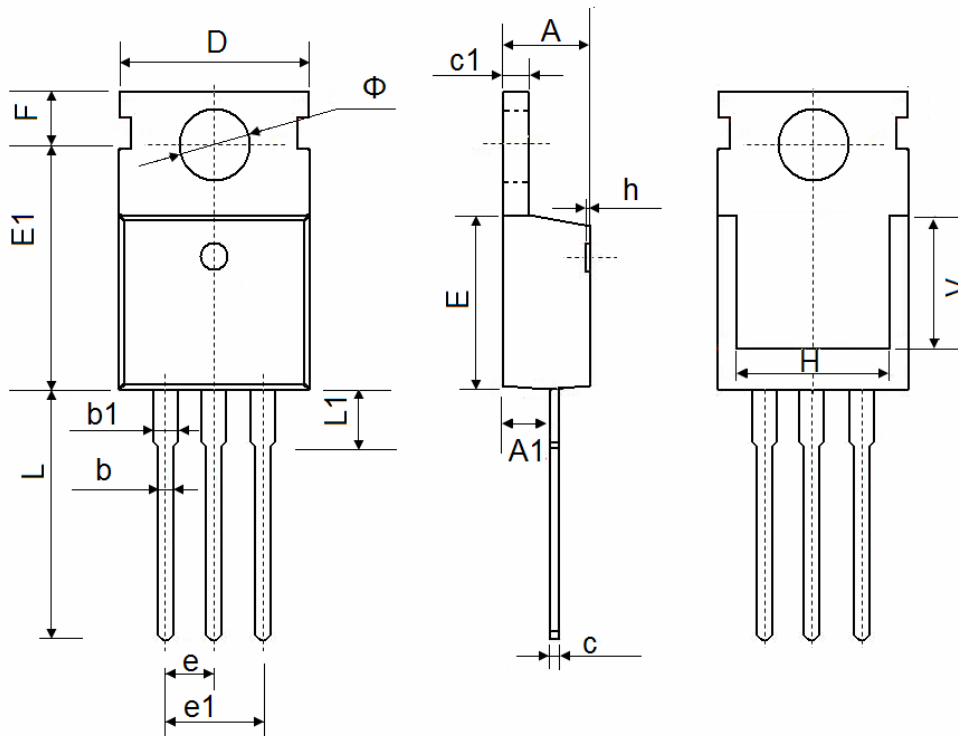
**Fig.8 Body-diode Characteristic**



**Fig.9 Safe Operating Area**



**Fig.10 Normalized Maximum Transient Thermal Impedance**

**P-Channel Enhancement Mode MOSFET**
**TO-220 Package Outline Data**


Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.350	4.650
A1	2.250	2.550
b	0.710	0.910
b1	1.170	1.400
c	0.330	0.650
c1	1.200	1.400
D	9.910	10.250
E	8.9500	9.750
E1	12.650	12.950
e	2.540 TYP.	
e1	4.980	5.180
F	2.650	2.950
H	7.900	8.100
h	0.000	0.300
L	12.700	13.500
L1	2.850	3.250
V	7.500 REF.	
Φ	3.400	3.800